- Standard '16245-Type Pinout
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages

description

The SN74CBTR16245 provides 16 bits of high-speed TTL-compatible bus switching in a standard '16245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 8-bit low-impedance switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and data can flow from port A to port B, or vice versa. When \overline{OE} is high, the switch is open, and a high-impedance state exists between the two ports.

The device has equivalent 25- Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16245 is characterized for operation from –40°C to 85°C.

(TOP VIEW) NC 48 1 1 OF 47 🛮 1A1 1B1 🛚 1B2 🛮 3 46 1 1A2 GND 4 45 GND 1B3 🛮 5 44 1 1A3 1B4 🛮 6 43 1 1A4 V_{CC} **↓** 7 42 V_{CC} 1B5 🛮 8 41 1 1A5 40 [] 1A6 1B6 📙 9 **GND** 10 39 GND 1B7 🛮 11 38 🛮 1A7 37 1 1A8 1B8 🛮 12 2B1 | 13 36 | 2A1 2B2 14 35 2A2 GND 15 34 GND 2B3 16 33 2A3 2B4 🛮 17 32 | 2A4 31 [] V_{CC} V_{CC} 18 2B5 19 30 2A5 2B6 🛮 20 29 2A6 GND 21 28 GND 2B7 [22 27 | 2A7 2B8 🛮 23 26 2A8 NC 24 25 20E

DGG, DGV, OR DL PACKAGE

NC - No internal connection

FUNCTION TABLE (each 8-bit bus switch)

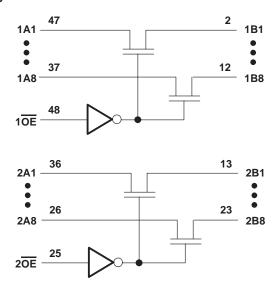
INPUT OE	FUNCTION
L	A port = B port
Н	Disconnect



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

, , ,	
	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D	GG package 70°C/W
D	GV package 58°C/W
D	L package 63°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level control input voltage	2		V
VIL	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	PARAMETER TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT			
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2	V	
II		$V_{CC} = 0$	V _I = 5.5 V				10	μА	
		V _{CC} = 5.5 V	V _I = 5.5 V or GND				±1		
Icc		V _{CC} = 5.5 V,	I _O = 0,	$V_I = V_{CC}$ or GND			3	μΑ	
Δl _{CC} ‡	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA	
Ci	Control inputs	V _I = 3 V or 0						pF	
C _{io(OFF}	=)	$V_{O} = 3 \text{ V or } 0,$	OE = V _{CC}					pF	
r _{on} §		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω	
				I _I = 30 mA			·		
			V _I = 2.4 V,	I _I = 15 mA			·		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

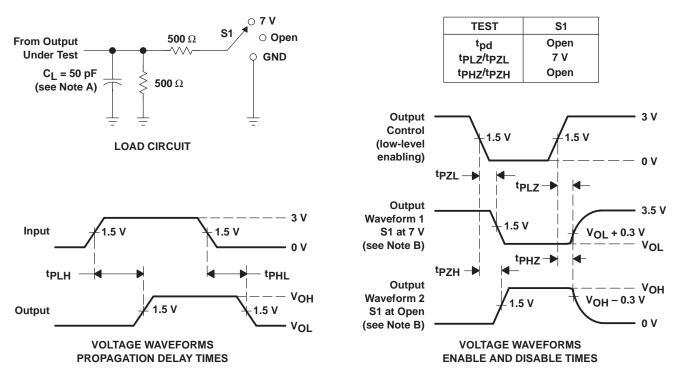
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN MAX	UNIT
t _{pd} ¶	A or B	B or A		ns
t _{en}	ŌĒ	A or B		ns
^t dis	ŌĒ	A or B		ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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